

ALLIANCE GROUP TECHNOLOGIES

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HIGH-MIX, LOW-TO-MEDIUM VOLUME, AND QUICK-TURN ELECTRONIC ASSEMBLIES

What type of electronic assembly services do you offer? We provide services in four areas: Our core service is *Automated Surface Mount and Manual Through-hole Assembly*. We also provide *Custom Cable and Harness Assemblies*, *Build-to-Spec Test Boxes/Equipment racks*, and *Electronic Rework and Repair*.

How many assembly lines do you have? Our two surface mount lines utilize MYDATA® MY9 surface mount placement equipment which is designed for multiple set ups and tear downs, and quick program changeovers. These machines are followed by two reflow lines, a 7-zone and a 5-zone oven, to support both tin-lead and lead-free process builds. Through-hole components are manually placed on our slide line and are either soldered by hand or wave soldered, depending on volume and process (tin-lead or lead-free).

What information do you need to quote a printed circuit board assembly? To provide a competitive proposal, our quote staff would like to have any electronic assembly and board information available. Three critical items include an assembly drawing, gerbers, and a bill of materials file (with the name of the manufacturer and the manufacturer's part number). In addition to quantity and number of releases/turn-time requirements, we also need to know who is supplying which materials (boards, components, etc.). We can provide full turn-key services if needed. You can also locate a check-list at http://www.alliancegroup-inc.com/docu/AGTC_deliverables.pdf

Are you doing lead-free builds? Yes. We support low-volume lead-free builds through our automation and manual through-hole processes. Through-hole components are manually placed and soldered with lead-free solder.

What is 'low to medium volume' for Alliance Group Technologies Co.? Low to medium volume is one unit (automated or hand-built) to several thousand per year. This can be driven by any one of the following limiting factors: number of unique line items on the bill of materials, technology, product mix, required product turn-time, and available resource capacity.

Can you place ball grid arrays (BGAs) and chip-scale components? We are placing BGAs and fine-pitch components (0402s, QFPs, leadless, etc.). All BGAs are 100% x-rayed for alignment verification.

Can you apply conformal coatings? We are providing conformal coating processes using a hand spray application. If required, individual components will be masked.

What standard are you building your products to? Alliance Group Technologies is currently building products to meet IPC Class II standards. Our employees have received both IPC-J-STD-001 and IPC-A-610 training.

Can you functionally test the printed circuit board assemblies? Yes. We use functional test equipment and setups designed and/or built by Alliance Group Technologies Co. and/or on equipment supplied by our customers.

Who is part of your customer base? Our customer base includes venture/private/university-funded start-up companies to industry-leading Original Equipment Manufacturers (OEMs) that make up the Fortune 500. These customers represent multiple industry segments such as consumer, transportation, automation, military, medical equipment, automotive, and industrial products.